

In the Specification

Page 38 and continuing through page 39, paragraph beginning at line 17, has been rewritten as indicated below:

B1  
The resin-sealed package is shown in Fig. 19. The IC 65 is bonded to the nickel-plated radiator plate 67 of the present invention with the Au-Si alloy 66. It is further bonded to the copper grounding plate 69 and the nickel-plated radiator plate 70 of the present invention with the heat-conductive resin 68. On the other hand, the terminal of the IC is connected to the TAB 72 (including layers 72A and 72B) through the Au bump 71 and sealed with the resin 73. The lead frame 57 and the radiator plate are partly exposed to the outside from the sealing resin. The TAB is fixed to the copper grounding plate with an epoxy-based silver paste 74.

In the Claims:

Please cancel claims 1-18 without prejudice.

Please add new claims 19-25 as follows:

B2  
-- 19. A composite material comprised of copper (Cu) and cuprous oxide ( $\text{Cu}_2\text{O}$ ), characterized in that said composite material contains said cuprous oxide in an amount of 20-80vol%, and said composite material is sintered.

20. A composite material according to claim 1,  
wherein said composite material has a coefficient of thermal expansion of  $5 \times 10^{-6}$  to  $14 \times 10^{-6}/\text{C}$ .